## DISCRETE SEMICONDUCTORS

# DATA SHEET

# **PDTC143E series** NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

Product specification Supersedes data of 2004 Jan 12 2004 Mar 18





**Philips Semiconductors** 

## NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTC143E series

#### **FEATURES**

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

#### **APPLICATIONS**

- · General purpose switching and amplification
- · Inverter and interface circuits
- · Circuit driver.

### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	_	50	V
Io	output current (DC)	_	100	mA
R1	bias resistor	4.7	_	kΩ
R2	bias resistor	4.7	_	kΩ

#### **DESCRIPTION**

NPN resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

#### **PRODUCT OVERVIEW**

TYPE NUMBER	PACE	(AGE	MARKING CODE <sup>(1)</sup>	PNP COMPLEMENT
I TPE NUMBER	PHILIPS	EIAJ	WARKING CODE	PNP COMPLEMENT
PDTC143EE	SOT416	SC-75	02	PDTA143EE
PDTC143EEF	SOT490	SC-89	51	PDTA143EEF
PDTC143EK	SOT346	SC-59	02	PDTA143EK
PDTC143EM	SOT883	SC-101	E1	PDTA143EM
PDTC143ES	SOT54 (TO-92)	SC-43	TC143E	PDTA143ES
PDTC143ET	SOT23	-	*02	PDTA143ET
PDTC143EU	SOT323	SC-70	*02	PDTA143EU

#### Note

<sup>1. \* =</sup> p: Made in Hong Kong.

<sup>\* =</sup> t: Made in Malaysia.

<sup>\* =</sup> W: Made in China.

# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTC143E series

## SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	CIMPLIFIED OUTLINE AND CYMPOL		PINNING
TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PIN	DESCRIPTION
PDTC143ES	1 R1 R2 R2 R2 R2 R2	1 2 3	base collector emitter
PDTC143EE PDTC143EEF PDTC143EK PDTC143ET PDTC143EU	3 1 R1 R2 2 Top view  MDB269	1 2 3	base emitter collector
PDTC143EM	2 R1 R2 2 bottom view MHC506	1 2 3	base emitter collector

## NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTC143E series

#### **ORDERING INFORMATION**

TYPE NUMBER		PACKAGE	
I TPE NUMBER	NAME	DESCRIPTION	VERSION
PDTC143EE	_	plastic surface mounted package; 3 leads	SOT416
PDTC143EEF	_	plastic surface mounted package; 3 leads	SOT490
PDTC143EK	_	plastic surface mounted package; 3 leads	SOT346
PDTC143EM	_	leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm	SOT883
PDTC143ES	_	plastic single-ended leaded (through hole) package; 3 leads	SOT54
PDTC143ET	_	plastic surface mounted package; 3 leads	SOT23
PDTC143EU	_	plastic surface mounted package; 3 leads	SOT323

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	10	V
VI	input voltage				
	positive		_	+30	V
	negative		_	-10	V
Io	output current (DC)		_	100	mA
I <sub>CM</sub>	peak collector current		_	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C			
	SOT54	note 1	_	500	mW
	SOT23	note 1	_	250	mW
	SOT346	note 1	_	250	mW
	SOT323	note 1	_	200	mW
	SOT416	note 1	_	150	mW
	SOT883	notes 2 and 3	_	250	mW
	SOT490	notes 1 and 2	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

### **Notes**

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu m$  copper strip line.

# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTC143E series

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air		
	SOT54	note 1	250	K/W
	SOT23	note 1	500	K/W
	SOT346	note 1	500	K/W
	SOT323	note 1	625	K/W
	SOT416	note 1	833	K/W
	SOT883	notes 2 and 3	500	K/W
	SOT490	notes 1 and 2	500	K/W

#### **Notes**

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu m$  copper strip line.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 50 V; I <sub>E</sub> = 0 A	_	_	100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	V <sub>CE</sub> = 30 V; I <sub>B</sub> = 0 A	_	_	1	μΑ
		$V_{CE} = 30 \text{ V}; I_{B} = 0 \text{ A}; T_{j} = 150 ^{\circ}\text{C}$	_	_	50	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; I_{C} = 0 \text{ A}$	_	_	900	μΑ
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 5 V; I <sub>C</sub> = 10 mA	30	_	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = 10 \text{ mA}; I_B = 0.5 \text{ mA}$	_	_	150	mV
$V_{i(off)}$	input-off voltage	$I_C = 100 \mu\text{A};  V_{CE} = 5 \text{V}$	_	1.1	0.5	٧
V <sub>i(on)</sub>	input-on voltage	$I_C = 20 \text{ mA}; V_{CE} = 0.3 \text{ V}$	2.5	1.9	_	٧
R1	input resistor		3.3	4.7	6.1	kΩ
R2 R1	resistor ratio		0.8	1	1.2	
C <sub>c</sub>	collector capacitance	$I_E = I_e = 0 \text{ A}; V_{CB} = 10 \text{ V};$ f = 1 MHz	_	_	2.5	pF

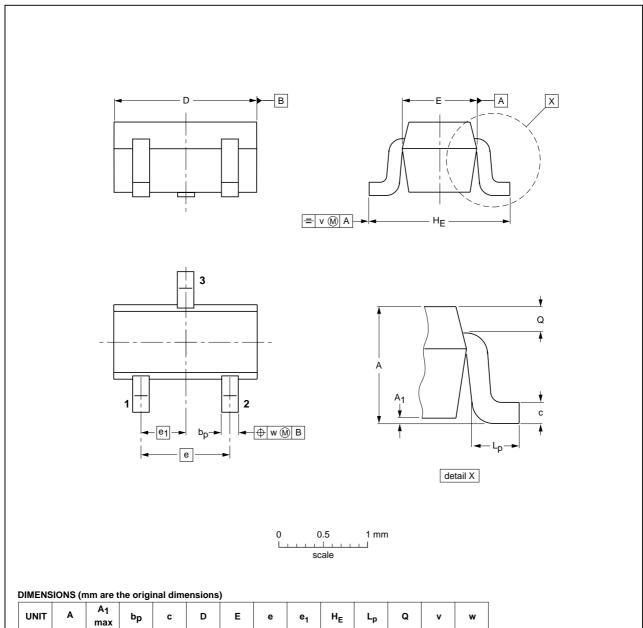
# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTC143E series

#### **PACKAGE OUTLINES**

### Plastic surface mounted package; 3 leads

**SOT416** 



OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT416			SC-75		97-02-28	

1.75

0.5

0.45

0.23

0.2

0.2

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0.30

0.95

0.25

0.10

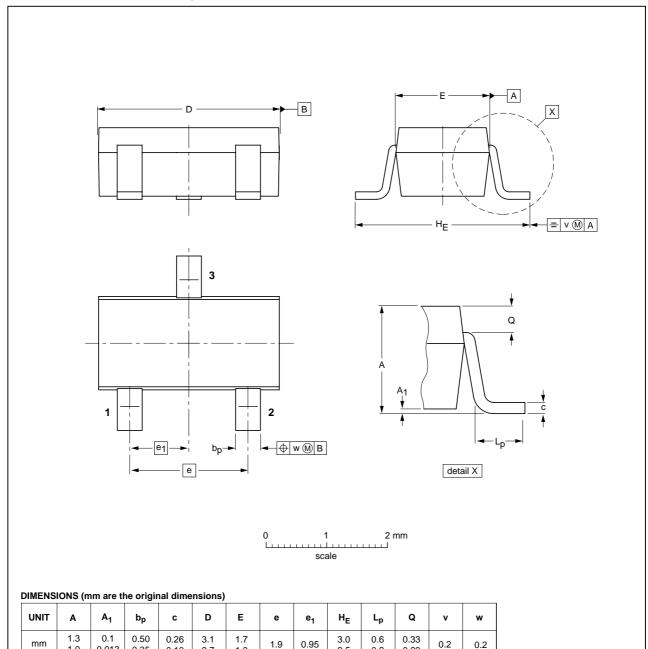
1.8

# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTC143E series

### Plastic surface mounted package; 3 leads

**SOT346** 



OUTLINE		REFER	ENCES	EUROPEAN ISSUE DAT		
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT346		TO-236	SC-59		98-07-17	

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1.0

0.013

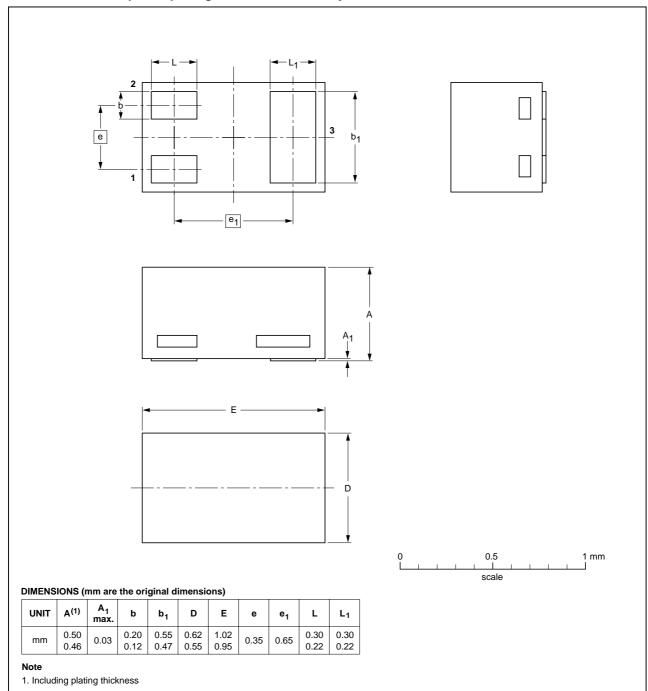
0.35

# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTC143E series

### Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

**SOT883** 



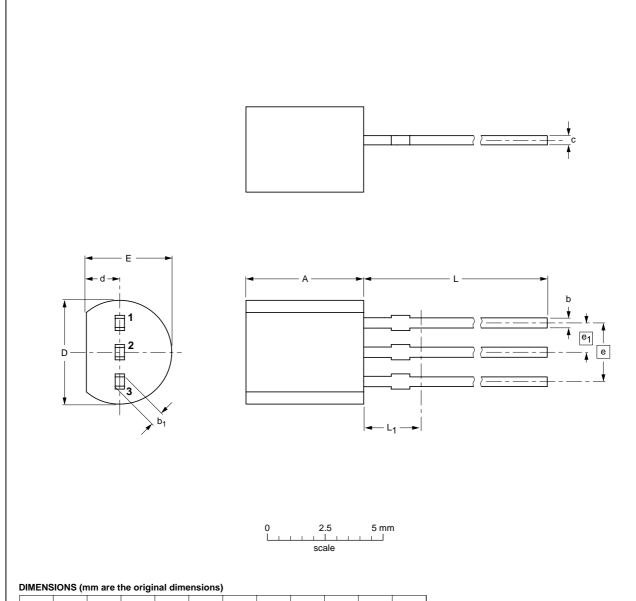
OUTLINE		REFER	ENCES	EUROPEAN ISSUE DAT			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT883			SC-101			<del>03-02-05</del> 03-04-03	

# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTC143E series

### Plastic single-ended leaded (through hole) package; 3 leads

SOT54



UNIT	A	b	b <sub>1</sub>	С	D	d	E	е	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup>
mm	5.2 5.0	0.48 0.40	0.66 0.56	0.45 0.40	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

#### Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

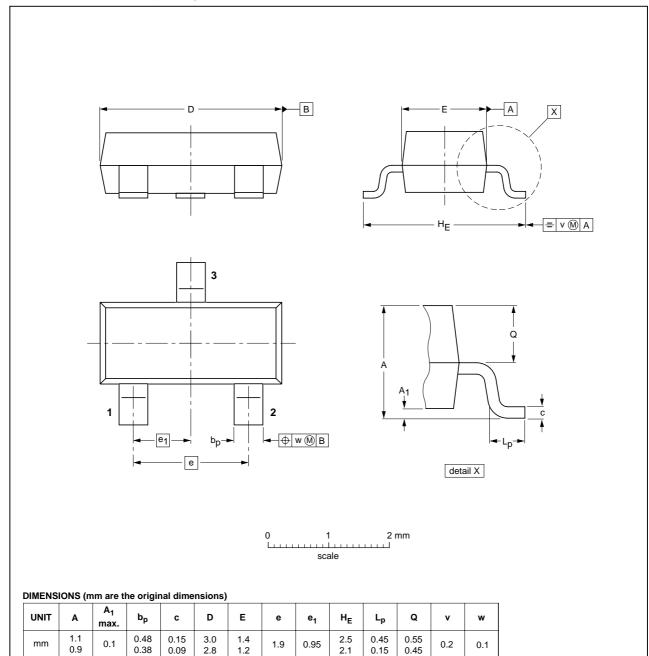
OUTLINE		REFER	FERENCES EUROPEAN ISS		ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT54		TO-92	SC-43			97-02-28	

# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTC143E series

### Plastic surface mounted package; 3 leads

SOT23



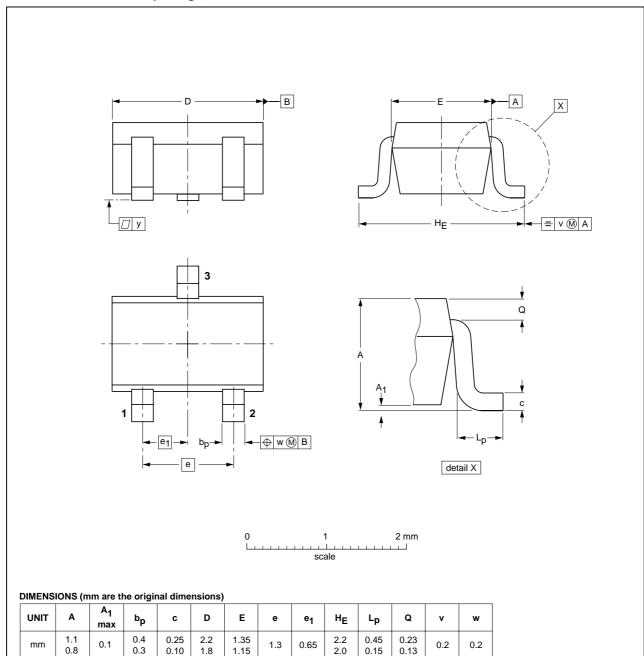
OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT23		TO-236AB				<del>-97-02-28-</del> 99-09-13

# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

## PDTC143E series

### Plastic surface mounted package; 3 leads

**SOT323** 



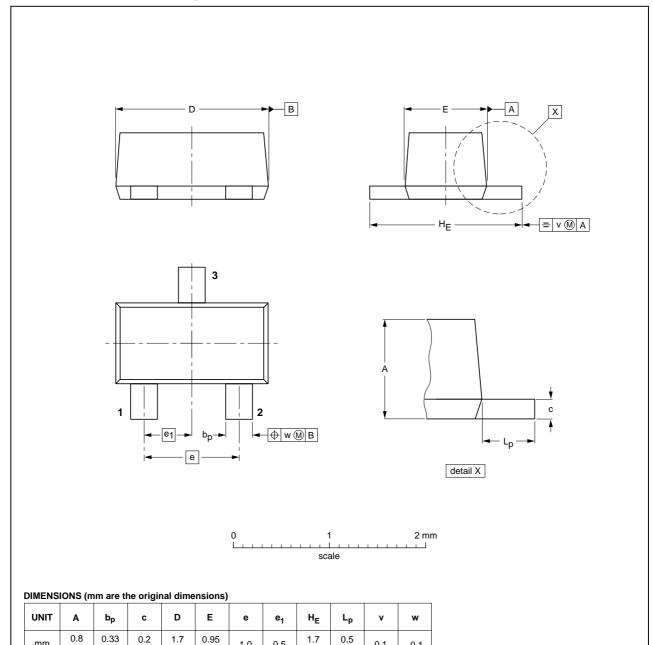
OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT323			SC-70			97-02-28

## NPN resistor-equipped transistors; $R1 = 4.7 \text{ k}\Omega$ , $R2 = 4.7 \text{ k}\Omega$

## PDTC143E series

### Plastic surface mounted package; 3 leads

**SOT490** 



OUTLINE	REFERENCES				EUROPEAN	IOOUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT490			SC-89			98-10-23

0.1

0.1

1.0

0.5

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0.6

## NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 4.7 k $\Omega$

### PDTC143E series

#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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